IN THE SPECIFICATION

The specification has been amended, as follows, at page 1, lines 1 - 3 as follows:

~~PROBE PIN FOR TESTING ELECTRICAL CHARACTERISTICS OF APPARATUS, PROBE CARD USING THE PROBE PINS, AND METHOD FOR FABRICATING THE PROBE PIN.~~ METHOD FOR FABRICATING A PROBE PIN FOR TESTING ELECTRICAL CHARACTERISTICS OF AN APPARATUS

The specification has been amended, as follows, at page 1, line 4.

RELATED APPLICATIONS

This application is a divisional application of U.S. patent application serial No. 09/733,228, filed December 8, 2000, now U.S. Patent No. 6,724,208.

The specification has been amended at page 6, line 15, as follows:

~~Fig. 3 illustrates~~ Fig. 3A, 3B, 3C, 3D, 3E, 3F, 3G, and 3H illustrate

The specification has been amended at page 6, line 16, as follows:

~~Fig. 4 illustrates~~ Fig. 4A and 4B illustrate

The specification has been amended at page 6, line 22, as follows:

~~Fig. 6 illustrates~~ Fig. 6A, 6B, 6C, and 6D illustrate

The specification has been amended at page 10, line 30 - page 11, line

15, as follows:

Fig. 4B illustrates probe card 200, which is another example of the application of the probe pin of the present invention. The second face (i.e., the bottom faces) of the probe pins are connected to the electrodes ~~301 through 303~~ 291 - 293 by an adhesive layer 305 in place of, or together with solder balls 281, 282, 283. The adhesive layer 305 may be a bonding agent or a thermoplastic resin used in a semisolid state. In either case, a bonding agent or a semisolid resin is applied on the print board 120 using, for example, a squeegee so as not to hide the electrodes 291, 292, 293. The bonding agent or the semisolid resin is swelled up on the print board 120. Then, the second faces (i.e., the bottom faces) of the probe pins are positioned directly above the electrodes, and brought into contact with the electrodes. At this time, the bottom face of the insulating layer 25 is pressed against the swelling bonding agent or resin. As a result, the bonding agent is flattened in the horizontal direction, an even adhesive layer 305 is formed between the polyimide insulating layer 25 and the print wiring board 120. The adhesive 305 hardens as time passes, and the polyimide insulating layer 25 is fixed to the print wiring board 120. This arrangement guarantees electric connection between the probe pins and the electrodes are filled with the adhesive layer 305 to seal up the mechanical connection between the probe pin and the electrodes.